

CLAIMS

1. A method for drying circuit substrates (13), in particular semiconductor substrates, in which a circuit surface (29, 30) of the circuit substrate is flushed using a flushing liquid (10) in a flushing step and the circuit surface is dried in a subsequent drying step, the circuit substrate being moved in the flushing step in the direction of its planar extension transversely and in relation to a liquid level (28) of the flushing liquid in such way that a liquid meniscus (31, 32) forms at a transition area (35) between the circuit surface and the liquid level, which changes because of the relative movement, and thermal radiation (36) is applied to the transition area wetted by the liquid meniscus in the drying step.
2. The method according to Claim 1, characterized in that thermal radiation (36) is applied using an infrared radiator.
3. The method according to Claim 1 or 2, characterized in that to perform the relative movement between the liquid level (28) and the circuit substrate (13), the circuit substrate is situated in the flushing liquid (10) received by bath container (11) and the liquid level is lowered.
4. The method according to one of the preceding claims, characterized in that thermal radiation (36) is applied transversely to the liquid level (28).
5. The method according to one of the preceding claims, characterized in that

the ventilation of a container lumen (33) implemented above the liquid level (28) occurs essentially parallel to the liquid level (28).

6. The method according to one of the preceding claims,
5 characterized in that
multiple flushing steps are performed through repeated flooding of the bath container before performing the drying step in the bath container (11).
- 10 7. A device for performing a method for drying circuit substrates (13), in particular semiconductor substrates, according to one more of Claims 1 through 6, having a bath container (11), which is provided with an inflow unit (16) and an outflow unit (17) and is closable using a cover unit (20), and a receiving system (12),
15 which is situated in the bath container, for receiving at least one circuit substrate in such a way that the circuit substrate extends in a plane in the direction of a container floor (14), and having a thermal radiator unit (22) situated above the receiving system.
- 20 8. The device according to Claim 7,
characterized in that
the thermal radiator unit (22) is provided with infrared radiators.
9. The device according to Claim 7 or 8,
25 characterized in that
the thermal radiator unit (22) is situated on the cover unit (20).
10. The device according to one more Claims 7 through 9,
characterized in that
30 the thermal radiator unit (22) is situated above a transparent plate (25) for separation from a container interior.

11. The device according to one of Claims 7 through 10,
characterized in that
the bath container (11) is provided in the area of the cover unit
(20) with a ventilation unit (27).

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12. The device according to Claim 11,
characterized in that
the ventilation unit (27) is situated on the cover unit (20).